

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) An electrical ~~multilayer~~ component having multiple layers (1), the electrical [[-]] comprising at least one of a capacitor, a temperature-dependent resistor, and a varistor, said multilayer component comprising:

~~[[ -]] a main body (5) constructed from stacked dielectric layers~~ that are stacked to form a main body;[[,]]

~~[[ -]] multiple electrode areas~~ electrodes positioned ~~in the main body~~ at intervals between at least some of the dielectric material layers; ~~[[,]] in which areas electrodes (10A, 15A) are formed,~~

~~[[ -]] at least two bumps (10, 15) for the~~ configured to act as electrical contacts for contact of the electrical component, which the bumps are positioned being on the a surface of the main body; and (5),

~~[[ -]] the bumps (10, 15) being electrically connected to at least one of said electrodes (10A, 15A) via through contacts (6) arranged in the main body~~[[,]] that electrically connect bumps and electrodes;

wherein the electrodes comprise first and second electrode stacks, so that a first and a second electrode stack (10B, 15B) are formed, wherein each of said first and second

~~stack contacts only~~ the first and second electrode stacks contacting one of said the bumps  
~~(10, 15).~~

2. (Currently Amended) The electrical multilayer component ~~according to~~ of  
claim 1, ~~[[ - ]]~~ wherein a first contact electrically connects electrodes in the first electrode  
stack to a bump, and a second contact electrically connects electrodes in the second  
electrode stack to a bump ~~a plurality of electrodes (10A) is provided in same electrode~~  
~~stack (10B), said electrodes being arranged in different electrode areas,~~

~~[[ - ]]~~ ~~said electrodes (10A) being connected to one another in an electrically~~  
~~conductive way using said through contacts (6).~~

3. (Currently Amended) The electrical multilayer component of claim 1 ~~(1)~~  
~~according to one of the preceding claims, [[ - ]]~~ wherein ~~said the~~ first and second electrode  
stacks ~~(10B, 15B)~~ face one another each other in the main body; and (5),

~~[[ - ]]~~ wherein the main body comprises a ~~an electrode free~~ region ~~(11) of the main~~  
~~body (5) is provided~~ between the ~~two~~ first and second electrode stacks that does not  
contain an electrode.

4. (Currently Amended) The electrical multilayer component of claim 1 ~~according~~  
~~to one of claims 1 or 2, [[ - ]]~~ wherein ~~the~~ electrodes ~~(10A, 15A) of~~ from the first and second  
~~stack~~ electrode stacks overlap ~~one another.~~

5. (Currently Amended) The electrical multilayer component of claim 1 ~~(1)~~  
~~according to one of the preceding claims, [[-]] wherein~~ further comprising:  
floating electrodes ~~(60) are provided~~ in the main body ~~(5)~~, wherein ~~said~~ the floating  
electrodes do not contact ~~any of~~ the bumps ~~(10, 15)~~.

6. (Currently Amended) The electrical multilayer component of claim 5 ~~according~~  
~~to the preceding claim, [[-]] wherein~~ the floating electrodes ~~(60)~~ overlap ~~with the~~  
electrodes ~~(10A, 15A)~~ of from at least one of the first ~~(10B)~~ and ~~the~~ second electrode  
stacks ~~(15B)~~.

7. (Currently Amended) The electrical multilayer component of claim 1 ~~(1)~~  
~~according to one of the preceding claims, [[-]] further comprising:~~  
~~wherein~~ a third bump ~~(20) is provided on the~~ a surface of the main body; ~~and~~ [[,]]  
~~[[ - ]]~~ ~~wherein at least one~~ a third electrode stack ~~(20B) is provided~~ in the main body  
~~(5)~~, ~~said~~ the third electrode stack comprising at least one electrode ~~(20A)~~, ~~wherein said the~~  
third electrode stack ~~is connected in an electrically conductive way to~~ being electrically  
connected to the third bump ~~(20)~~ via a contact; ~~through contacts (6)~~;  
~~[[ - ]]~~ wherein the at least one electrode ~~(20A)~~ of in the third electrode stack ~~(20B)~~  
~~overlapping overlaps with~~ an electrode ~~(10A, 15A)~~ of in at least one of the first ~~(10B)~~ and  
~~the~~ second electrode stacks ~~(15B)~~.

8. (Currently Amended) The electrical multilayer component ~~according to~~ of claim 7, ~~[[ - ]]~~ wherein ~~the~~ electrodes ~~(10A, 15A)~~ of in the first ~~(10B)~~ and the second electrode stacks ~~(15B)~~ do not overlap ~~one another~~.

9. (Currently Amended) The electrical multilayer component of claim 7 ~~according to one of preceding claims 7 or 8~~, ~~[[ - ]]~~ wherein the first ~~(10B)~~, second ~~(15B)~~, and third electrode stacks ~~(20B)~~ each comprise one electrode ~~(10A, 15A, 20A)~~.

10. (Currently Amended) The electrical multilayer component of claim 7 ~~according to one of claims 7 through 9~~, ~~[[ - ]]~~ wherein the overlap areas ~~(21, 22)~~ between the electrodes ~~of different pairs of~~ from different electrode stacks ~~(10B, 15B, 20B)~~ have different sizes ~~with respect to one another~~.

11. (Currently Amended) The electrical multilayer component of claim 7 ~~according to the preceding claim~~, ~~[[ - ]]~~ wherein the electrode overlap areas ~~(21, 22)~~ between the third electrode stack ~~(20B)~~ and the first electrode stacks ~~(10B)~~ have different sizes ~~with respect to the~~ than electrode overlap areas ~~(21, 22)~~ between the third electrode stack ~~(20B)~~ and the second electrode stack ~~(15B)~~.

12. (Currently Amended) The electrical multilayer component of claim 7 ~~according to one of claims 7 through 11~~, further comprising:

[[ -]] ~~wherein~~ a fourth bump on a surface of the main body; (25) and fifth bump (30) are provided on the surface of the main body (5);

a fifth bump on a surface of the main body;

[[ -]] ~~wherein~~ a fourth ~~(25B) and a fifth~~ electrode stack ~~(30B)~~ comprising electrodes in the main body; (25A, 30A) are provided;

a fifth electrode stack comprising electrodes in the main body; and

[[ -]] ~~wherein~~ contacts that contact the forth fourth electrode stack ~~(25B)~~ is ~~connected to the fourth bump (25) via through contacts (6), and wherein~~ and that contact the fifth electrode stack ~~(30B)~~ is connected to the fifth bump; (30) via through contacts (6);

[[ -]] wherein ~~the~~ electrodes ~~(25A) of in~~ the fourth electrode stack ~~(25B)~~ ~~overlapping with the~~ overlap electrodes ~~(15A) of in~~ the second electrode stack ~~(15B)~~ and ~~the electrodes (30A) of in~~ the fifth electrode stack ~~(30B)~~.

13. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of the preceding claims,~~ further comprising:

[[ - wherein further]] additional bumps ~~are provided~~ on the surface of the main body; and [[,]]

[[ - wherein further]] additional electrode stacks ~~are provided~~ in the main body, ~~said~~ ~~further~~ each of the additional electrode stacks being ~~each~~ connected to a corresponding additional ~~respective further~~ bump.

14. (Currently Amended) The electrical multilayer component ~~according to~~ of claim 13, ~~[[ - ]]~~ wherein at least some ~~of the~~ electrodes ~~(20A, 80A)~~ of from different electrode stacks ~~(20B, 80B)~~ are electrically connected to one another ~~in an electrically conductive way~~.

15. (Currently Amended) The electrical multilayer component of claim 12 ~~according to one of the preceding claims, [[ - ]]~~ wherein all bumps are ~~positioned on the~~ on a same main surface of the main body.

16. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of the preceding claims, [[ - ]]~~ wherein the dielectric layers comprise a ceramic material.

17. (Currently Amended) The electrical multilayer component ~~according to~~ of claim 16, ~~[[ - ]]~~ wherein the ceramic material comprises a varistor ceramic based on one of ZnO-Bi and ZnO-Pr.

18. (Currently Amended) The electrical multilayer component ~~according to~~ of claim 16, ~~[[ - ]]~~ wherein the ceramic material comprises a capacitor ~~ceramics which~~ ceramic comprising is one of NPO ceramics and doped BaTiO<sub>3</sub>.

19. (Currently Amended) The electrical multilayer component ~~according to~~ of claim 16, ~~[[ - ]]~~ wherein the ceramic material comprises at least one of nickel, manganese, spinel, and perovskite.

20. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of the preceding claims, [[ - ]]~~ wherein the dielectric layers comprise glass.

21. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of the preceding claims, further comprising:~~  
at least three additional bumps on the ~~[[ - ]]~~ ~~wherein at least five bumps are provided~~  
~~on same main~~ surface of the main body; and ~~[[, ]]~~

at least three additional ~~[[ - ]]~~ ~~wherein at least 5 electrode stacks are provided in the~~  
main body, ~~said stacks being connected to a respective~~ each of the electrode stacks being  
electrically connected to a corresponding bump;~~[[, ]]~~

~~[[ - ]]~~ wherein the main body has an area ~~which is smaller~~ of less than 2.5 mm<sup>2</sup>.

22. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of claims 1 through 20, further comprising:~~  
at least seven additional ~~[[ - ]]~~ ~~wherein at least nine bumps are provided on same~~  
~~main~~ the surface of the main body; and ~~[[, ]]~~



at least seven additional ~~[[ - ]]~~ ~~wherein at least 9 electrode stacks are provided~~ in the main body, ~~said~~ each of the electrode stacks being electrically connected to a corresponding ~~respective~~ bump; ~~[[ , ]]~~

~~[[ - ]]~~ wherein the main body has an area ~~which is smaller~~ of less than 5.12 mm<sup>2</sup>.

23. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of claims 1 through 20~~, further comprising:

at least nine additional ~~[[ - ]]~~ ~~wherein at least eleven bumps are provided on same~~ main the surface of the main body; and ~~[[ , ]]~~

at least nine additional ~~[[ - ]]~~ ~~wherein at least 11 electrode stacks are provided~~ in the main body, ~~said stacks~~ each electrode stack being electrically connected to a respective corresponding bump; ~~[[ , ]]~~

~~[[ - ]]~~ wherein the main body has an area ~~which is smaller~~ of less than 8 mm<sup>2</sup>.

24. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of the preceding claims~~, ~~[[ - ]]~~ wherein the ~~through~~ contacts ~~(6A, 6B)~~ are ~~provided in the form of~~ comprise channels in the main body, ~~in which channels that~~ contain an electrically conductive material ~~is arranged~~.

25. (Currently Amended) The electrical multilayer component ~~according to~~ of claim 24, ~~[[ - ]]~~ wherein the ~~through holes~~ channels have one of a round and a rectangular cross-section.



26. (Currently Amended) The electrical multilayer component of claim 1 ~~according to one of claims 24 or 25, further comprising:~~  
additional contacts in the main body [[-]] wherein the that electrically interconnect  
~~connect electrodes of a respective in a single electrode stack are connected to one another~~  
~~in an electrically conductive way by a plurality of through contacts, said through the~~  
additional contacts being arranged in different dielectric layers and being offset to from  
one another, the electrical component comprising first additional contacts for the first  
electrode stack and second additional contacts for the second electrode stack.

27. (Currently Amended) The electrical multilayer component ~~according to of~~  
claim 26, [[-]] wherein the main body has two opposite main surfaces ~~(300, 400)~~ and two  
front faces ~~(500, 600)~~, the bumps ~~(10, 15)~~ being ~~positioned~~ on the main surfaces; and (300,  
400),

[[ -]] wherein ~~through~~ contacts ~~(6A) arranged closest~~ closer to the bumps ~~(10, 15)~~  
~~have~~ are at a greater distance to from neighboring front faces ~~(500, 600)~~ of the electrical  
component than ~~the through~~ contacts ~~(6B) arranged further~~ farther away from the bumps  
~~(10, 15).~~

28. (Currently Amended) The electrical multilayer component ~~according to of~~  
claim 24, [[-]] wherein the electrically conductive material comprises at least one of Ag,  
AgPd, AgPt, AgPdPt, Pd, Pt, and Cu.

29. (Currently Amended) An arrangement ~~containing a~~ comprising:  
the electrical multilayer component of claim 1; and (1) according to one of the  
preceding claims;

[[ - ]] ~~comprising~~ a carrier substrate (100) ~~and~~ comprising contact pads (90) for  
~~contacting~~ connecting to the electrical component, said the contact pads being ~~arranged on~~  
~~the a~~ surface of ~~said the~~ carrier substrate; [[ , ]]

[[ - the multilayer ]] wherein the electrical component being is mounted on the  
carrier substrate (100) in a flip chip arrangement with clearance relative to said the carrier  
substrate; and [[ , ]]

[[ - said multilayer ]] wherein the electrical component is electrically connected to  
~~being connected to said carrier substrate in an electrically conductive way via~~ the contact  
pads (90) ~~by means of said~~ via the bumps (10, 15, 20).

30. (Currently Amended) A method for manufacturing ~~a multilayer~~ an electrical  
component comprised of multiple layers, said method the method comprising ~~the~~  
~~following steps:~~

[[ A )]] forming a main body (5) ~~having~~ comprising dielectric layers, electrodes,  
(10A, 15A) and ~~through~~ contacts (6A, 6B) arranged in ~~the~~ an interior of ~~said the~~ main  
body, ~~is produced in that a layer stack is provided of the~~ electrodes being (10A, 15A)  
~~positioned~~ between at least some of the dielectric layers, ~~said the~~ dielectric layers having

through holes[[,]] that contain an electrically conductive material that forms the contacts,  
and being provided in the through holes,

[[B)]] forming bumps (10, 15) are produced directly on the ~~respective through~~  
contacts.

31. (Currently Amended) The method ~~according to~~ of claim 30, [[-]] wherein ~~in~~  
~~step A) a~~ the main body ~~having~~ has two main surfaces ~~(300, 400)~~ and at least two front  
faces ~~(500, 600) is produced,~~ the ~~through~~ contacts comprising (6A, 6B) being produced in  
~~the form of~~ channels in the interior of the main body ~~(5) running that run~~ transversely to  
the main surfaces; and [[,]]

[[ -]] wherein ~~in step B)~~ the bumps are ~~produced~~ formed on the main surfaces.

32. (Currently Amended) The method of claim 30 ~~according to one of claims 30~~  
~~or 31,~~ [[-]] wherein ~~in step A)~~ the ~~through~~ contacts ~~(6A, 6B) are produced~~ formed in  
different dielectric ~~material~~ layers[[, through]] such that contacts ~~(6A, 6B) in~~ neighboring  
dielectric layers ~~being produced~~ are offset relative to each other ~~one another~~.

33. (Currently Amended) The method of claim 30 ~~according to one of claims 30~~  
~~through 32,~~ [[-]] wherein ~~in step A)~~ the ~~through~~ contacts ~~(6A) which~~ that are ~~closest~~ closer  
to the bumps ~~(10, 15) have~~ are at a greater distance ~~to~~ from neighboring front faces ~~(500,~~  
~~600)~~ than ~~through~~ contacts ~~(6B) which~~ that are ~~further~~ farther from the bumps ~~(10, 15)~~.